L Number	Hits	Search Text	DB	Time stamp
1	27	438/689.ccls. and ball\$2	USPAT;	2003/01/15 10:40
		, '	US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
2	20789	wafer near (remov\$3 or thin\$4 or etch\$3)	USPAT;	2003/01/15 10:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	6704	(- 5 (IBM_TDB	2000/05/15 11 05
3	6724	(wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:07
		and (glass or holder)	US-PGPUB; EPO; JPO;	
			DERWENT;	
-			IBM TDB	
4	4257	(wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:08
•	123,	and ((glass or holder) with (wafer or	US-PGPUB;	2003, 01, 13 11.00
		silicon))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	2407	((wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:10
		and ((glass or holder) with (wafer or	US-PGPUB;	
		silicon))) and (via or trench or cavity)	EPO; JPO;	
			DERWENT;	
	2.40		IBM_TDB	/ /
6	342	(((wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 12:59
		and ((glass or holder) with (wafer or	US-PGPUB;	
		silicon))) and (via or trench or cavity)) and ball\$2	EPO; JPO; DERWENT;	
		and ballyz	IBM TDB	
7	8198	(wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:07
1		and (glass or holder or chuck)	US-PGPUB;	2003, 01, 13 11.0,
		, , ,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	5782	(,	USPAT;	2003/01/15 11:08
		and (glass or holder or chuck)) and ((glass	US-PGPUB;	
		or holder or chuck) with (wafer or silicon))	EPO; JPO;	
			DERWENT;	
9	3184	(((wafer near (remov\$3 or thin\$4 or etch\$3))	IBM_TDB USPAT;	2003/01/15 11:10
	3104	and (glass or holder or chuck)) and ((glass	US-PGPUB;	2003/01/13 11:10
		or holder or chuck) with (wafer or	EPO; JPO;	
		silicon))) and (via or trench or cavity)	DERWENT;	
			IBM TDB	
10	477	((((wafer near (remov\$3 or thin\$4 or	USPAT;	2003/01/15 11:11
1		etch\$3)) and (glass or holder or chuck))	US-PGPUB;	
		and ((glass or holder or chuck) with (wafer	EPO; JPO;	
1		or silicon))) and (via or trench or cavity))	DERWENT;	
		and ball\$2	IBM_TDB	
11	392	(((((wafer near (remov\$3 or thin\$4 or	USPAT;	2003/01/15 12:06
		etch\$3)) and (glass or holder or chuck))	US-PGPUB;	
		and ((glass or holder or chuck) with (wafer	EPO; JPO;	
		or silicon))) and (via or trench or cavity)) and ball\$2) and (@ad<20010531)	DERWENT;	
L		and part92) and (@ad<20010231)	IBM_TDB	l

12	92	("3739463" "3810129" "3811117"	USPAT	2003/01/15 11:28
		"3838501" "3881884" "3991296"		,,
		"3993917"		
		"4368106"		
		"4467518" "4603341" "4612083"		
		"4628174"		
		"4769738" "4807021" "4822755"		
		"4842699" "4897708" "4954458"		
		"4978639" "4996587" "5024970"		
		"5064771" "5071792" "5135878"		
		"5160987" "5166097" "5191405"		
		"5225771" "5259924" "5268326"		
		"5270261" "5307942" "5309318"		
-		"5313097" "5314844" "5322816"		
		"5323035" "5340771" "5380681"		
		"5399898" "5414637" "5426566"		
		"5453404" "5463246" "5466634"		
		"5467305" "5468663" "5472914"		
		"5478781" "5489554" "5494832"		
		"5502333" "5502667" "5504036"		
		"5506753" "5517057" "5517754"		
		"5532519" "5550942" "5561622"		:
		"5563086" "5567653" "5567654"		
		"5571754" "5596226" "5627106"		
		"5646067" "5654127" "5656553"		
		"5691248" "5707485" "5766984"		
		"5824595" "5843844" "5846879"		
		"5851845" "5888882" "5888883"		
		"5979475" "5998292" "6004867"		
		"6083811" "6121119" "6162701"		
	_	"6176966" "6184060").PN.		
13	5	("5024970" "5223450" "5270261"	USPAT	2003/01/15 11:32
		"5346848" "5691248").PN.		
14	13	6004867.URPN.	USPAT	2003/01/15 11:32
15	4	("3508980" "4839309" "5013681"	USPAT	2003/01/15 11:37
-		"5091330").PN.		
18	41	5071792.URPN.	USPAT	2003/01/15 11:40
19	11	5903044.URPN.	USPAT	2003/01/15 11:59
21	336		USPAT;	2003/01/15 12:39
			US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
22	710	(water near (removed) on thinks on about 2))	IBM_TDB	2002/01/15 10 20
22	712	(wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 12:38
		and ((back near etch) or beol)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
23	668	(wafer near (remov\$3 or thin\$4 or etch\$3))	IBM_TDB	2002/01/15 10 20
23	000	and ((back near etch))	USPAT;	2003/01/15 12:39
		and ((back hear etch))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
24	593	((wafer near (remov\$3 or thin\$4 or etch\$3))	IBM_TDB	2002/01/15 12 52
24	593	and ((back near etch))) and (@ad<20010531)	USPAT;	2003/01/15 12:52
		and (back near ecchi)) and (wad<20010531)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
25	490	(((wafer near (remov\$3 or thin\$4 or etch\$3))	IBM_TDB USPAT;	2002/01/15 12 52
23	430	and ((back near etch))) and (@ad<20010531))		2003/01/15 12:50
		and (chip or die or package or ball\$2 or via	US-PGPUB;	
		or trench or groove or cavity)	EPO; JPO;	
		of tremen of groove of cavity)	DERWENT; IBM TDB	
26	o	(wafer near ball\$2) and ((trench or groove	· –	2003/01/15 12:52
20	٦	or cavity) near wafer)	USPAT; US-PGPUB;	2003/01/15 12:52
		or davidy, hear water,	EPO; JPO;	
			DERWENT;	
L			IBM_TDB	

27	109	(wafer near ball\$2)	USPAT;	2003/01/15 12:52
			US-PGPUB;	
			EPO; JPO;	
	}		DERWENT;	ı
			IBM TDB	
28	92	((wafer near ball\$2)) and (@ad<20010531)	USPAT;	2003/01/15 12:59
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	=====================================
			EPO; JPO;	
			DERWENT;	
			IBM TDB	i
29	135	438/For.403.ccls.	USPAT;	2003/01/15 13:04
		,	US-PGPUB;	2003, 01, 13 13:04
			EPO; JPO;	
			DERWENT:	
			IBM TDB	
30	135	438/For.403.ccls. and (@ad<20010531)	USPAT;	2003/01/15 13:05
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	2000, 01, 10 10:00
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
31	13	438/For.403.ccls. and (ball\$s or contact or	USPAT:	2003/01/15 13:04
		interconnect\$3)	US-PGPUB;	2000, 01, 15 15.01
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
32	468	438/977.ccls.	USPAT;	2003/01/15 13:04
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
33	319	438/977.ccls. and (ball\$s or contact or	USPAT;	2003/01/15 13:04
		interconnect\$3)	US-PGPUB:	
	•	·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
34	314	(438/977.ccls. and (ball\$s or contact or	USPAT;	2003/01/15 13:05
		interconnect\$3)) and (@ad<20010531)	US-PGPUB;	3,,3.03
			EPO; JPO;	
			DERWENT;	
			IBM TDB	